## Lightweight Metal RubberTM Sensors and Interconnects, Phase I



Completed Technology Project (2006 - 2006)

## **Project Introduction**

The objective of the proposed program is to develop lightweight and highly elastic electrically conducting interconnects and strain sensor arrays for next generation adaptive aerospace vehicles and structures. The systems-level problem this would solve is the inability of currently available materials to undergo the large strains and displacements associated with shape changes of morphing structures. NanoSonic will demonstrate the feasibility of the Metal RubberTM family of freestanding nanocomposite materials to serve as 1) electrically conductive, low modulus electrodes for large displacement mechanical actuators required to affect large shape changes, and 2) an integrated network of strain sensors to allow mapping of strain and determination of shape in adaptive structural components. Metal Rubber

TM

is fabricated via layer-by-layer, molecular self-assembly, which enables thickness and placement control over multiple molecular constituents for true nanostructured multifunctionality. As an electrode material, new, ultra-low modulus Metal Rubber

TM

can be strained to 1000% elongation while remaining electrically conductive; it returns to its original shape and nominal conductivity when released. As a strain sensor, strains up to 1000% have been measured in very highly flexible structures. During Phase I the feasibility of using such electrodes and strain sensors would be demonstrated in cooperation with a large aerospace company.

#### **Anticipated Benefits**

Potential NASA Commercial Applications: Metal Rubber

TM

can be used as replacements for conventional tin-lead solder for the mechanical, electrical and thermal interconnection of electronic and mechanical components. Similar materials may also be used in high performance, highly flexible and mechanically robust electronic flex circuits, flexible displays and smart electronic fabrics.



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# Organizational Responsibility

#### Responsible Mission Directorate:

Space Technology Mission Directorate (STMD)

#### **Lead Center / Facility:**

Langley Research Center (LaRC)

#### **Responsible Program:**

Small Business Innovation Research/Small Business Tech Transfer



### **Small Business Innovation Research/Small Business Tech Transfer**

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## **Primary U.S. Work Locations and Key Partners**



Organizations Performing Work	Role	Туре	Location
Langley Research Center(LaRC)	Lead Organization	NASA Center	Hampton, Virginia
Nanosonic, Inc.	Supporting Organization	Industry	Pembroke, Virginia

## **Primary U.S. Work Locations**

Virginia

# **Project Management**

**Program Director:** 

Jason L Kessler

**Program Manager:** 

Carlos Torrez

**Principal Investigator:** 

Andrea J Hill

# **Technology Areas**

#### **Primary:**

 TX12 Materials, Structures, Mechanical Systems, and Manufacturing

└─ TX12.1 Materials

☐ TX12.1.8 Smart Materials

